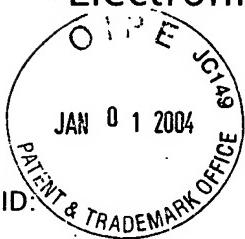




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53029

Application ID:

10605059



Title of Invention:

METHOD OF FORMING A HIGHLY
THERMALLY CONDUCTIVE AND
HIGH STRENGTH ARTICLE

First Named Inventor:

Kevin McCULLOUGH

Domestic/Foreign Application:

Domestic Application

Filing Date:

2003-09-05

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Filing Type:

Confirmation number:

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Attorney Docket Number:

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O I P E
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Stylesheet Version v1.1.0

O I P E
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P A T E N T & T R A D E M A R K O F F I C E

Title of Invention	METHOD OF FORMING A HIGHLY THERMALLY CONDUCTIVE AND HIGH STRENGTH ARTICLE	
Application Number:	10/605059 	
Date:	2003-09-05	
First Named Applicant:	Mr. Kevin A. McCULLOUGH	
Confirmation Number:	2058	
Attorney Docket Number:	C001P00472US2	
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Mr. David R. Josephs Registered Number: 34,632	/david r. josephs/	Attorney
Documents being submitted us-ids	Files P0472US2-usidst.xml us-ids.dtd us-ids.xsl	
Comments		

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

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Title of Invention	METHOD OF FORMING A HIGHLY THERMALLY CONDUCTIVE AND HIGH STRENGTH ARTICLE						
Application Number:	10/605059 						
Confirmation Number:	2058						
First Named Applicant:	Kevin McCULLOUGH						
Attorney Docket Number:	C001P00472US2						
Art Unit:	1714						
Search string:	(3398233 or 3673121 or 3708387 or 4098945 or 4307147 or 4367745 or 4496475 or 4568592 or 4664971 or 4689250 or 4816184 or 5011870 or 5011872 or 5021494 or 5098610 or 5098611 or 5106540 or 5171774 or 5180513 or 5183594 or 5213715 or 5225110 or 5286416 or 5302456 or 5334330 or 5373046 or 5397608 or 5445308 or 5490319 or 5522962 or 5536568 or 5580493 or 5669381 or 5681883 or 5770305 or 5834337 or 5851644 or 5863467 or 5945217 or 6048919 or 6251978 or 6251978 or 6303096 or 5037590 or 5552214 or 20020025998 or 20020022686).pn.						
US Patent Documents							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	3398233	1968-08-20	Lizasoain et al.			
	2	3673121	1972-06-27	Meyer	252	511	
	3	3708387	1973-01-02	Turner et al			
	4	4098945	1978-07-04	Oehmke	428	327	
	5	4307147	1981-12-22	Ohishi et al.	428	268	
	6	4367745	1983-01-11	Welage	128	303.13	
	7	4496475	1985-01-29	Abrams	252	514	
	8	4568592	1986-02-04	Kawaguchi et al.	428	107	
	9	4664971	1987-05-12	Soens	428	288	

	10	4689250	1987-08-25	Quella et al.		427	216
	11	4816184	1989-03-28	Fukuda et al.		252	511
	12	5011870	1991-04-30	Peterson		523	220
	13	5011872	1991-04-30	Latham et al.		523	440
	14	5021494	1991-06-04	Toya		524	404
	15	5098610	1992-03-24	Okamura et al.		252	511
	16	5098611	1992-03-24	Honda et al.		252	518
	17	5106540	1992-04-21	Barma et al.		252	511
	18	5171774	1992-12-15	Ueno et al.		524	495
	19	5180513	1993-01-19	Durand		252	62.55
	20	5183594	1993-02-02	Yoshinaka et al.		252	518
	21	5213715	1993-05-25	Patterson et al.		252	518
	22	5225110	1993-07-06	Kathirgamanathan		252	512
	23	5286416	1994-02-15	Teichmann et al.		252	512
	24	5302456	1994-04-12	Matsui		428	407
	25	5334330	1994-08-02	Rowlette		252	512
	26	5373046	1994-12-13	Okamura et al.		524	413
	27	5397608	1995-03-14	Soens		428	34.5
	28	5445308	1995-08-29	Nelson et al.		228	121
	29	5490319	1996-02-13	Nakamura et al.		29	596
	30	5522962	1996-06-04	Koskenmaki et al.		156	272.4
	31	5536568	1996-07-16	Teruo		428	327
	32	5580493	1996-12-03	Chu et al.		252	511
	33	5669381	1997-09-23	Hyatt		428	402
	34	5681883	1997-10-28	Hill et al.		524	404
	35	5770305	1998-06-23	Terasaka		428	328
	36	5834337	1998-11-10	Unger et al.		438	122
	37	5851644	1998-12-22	McArdle et al.		428	213
	38	5863467	1999-01-26	Mariner et al.		252	511
	39	5945217	1999-08-31	Hanrahan		428	389
	40	6048919	2000-04-11	McCullough		524	404
	41	6251978	2001-06-26	McCullough		524	404
	42	6251978	2001-06-26	McCullough		524	404
	43	6303096	2001-10-16	Yamamoto et al.	B1	423	447.2
	44	5037590	1991-08-06	Fukushima		264	29.2
	45	5552214	1996-09-03	Kobomura et al.		428	294

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20020025998	2002-02-28	McCullough	A1	524	66
	2	20020022686	2002-02-21	Itoh et al.	A1	524	504

Signature

Examiner Name	Date